

Abstract of the Disclosure

A heat dissipating structure of a printed circuit board on which a circuit pattern is provided so that a heat generating part can be mounted, and which has a through hole formed at a site where the heat generating part is mounted from a surface on which the heat generating part is mounted to the opposite surface. A heat dissipating member made of a material with a thermal conductivity higher than a board of the printed circuit board, and having a shape worked so that the heat dissipating member can be inserted into the through hole is mounted in the through hole with an adhesive interposed therebetween. Heat generated from a heat generating part is transferred by way of a heat dissipating member to as far as a conductor of the GND surface or heat dissipating fins.